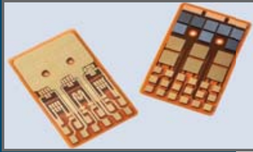
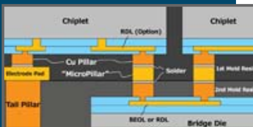
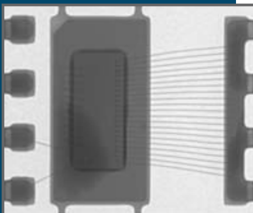
Advanced Packaging Update:

Market and Technology Trends

Vol. 1-0523







This issue of the Advanced Packaging Update features a detailed financial analysis of the top 20 OSATs. A special section examines the adoption of SiC and GaN, packaging trends, and OSAT activities. Market forecasts for Ball Grid Arrays (BGAs) and Chip Scaled Packages (CSPs) are provided in units. The CSP market is divided into laminate (FBGA and FLGA) and leadframe (QFN) substrates. Stacked die package trends are included. Unit growth projections for Cu clip and molded interconnect substrates (MIS) are provided. An update on supply and demand for the build-up substrate market is provided.

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Single issue – $2,500
Corporate license – $8,750 (4 issues)

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Contents and specifications subject to change without notice. 05/24/2023